

FR015L3EZ (15mΩ, -20V) Low-Side Reverse Bias / Reverse Polarity Protector

Features

- Up to -20V Reverse-Bias Protection
- Nano Seconds of Reverse-Bias Blocking Response Time
- +12V 24-Hour “Withstand” Rating
- 15mΩ Typical Series Resistance at 3.0V
- 18mΩ Typical Series Resistance at 2.1V
- Integrated TVS Over Voltage Suppression
- MicorFET2x2mm Package Size
- RoHs Compliant
- USB V_{BUS} Compatible

Applications

- 3V+ Battery Operated Systems
- Reverse Battery Protection
- 2 to 5 Cell Alkaline Battery Operated Systems
- USB 1.0, 2.0 and 3.0 Devices
- USB Charging
- Mobile Devices
- Mobile Medical
- Toys
- Any DC Barrel Jack Powered Device
- Any DC Devices subject to Negative Hot Plug or Inductive Transients

Description

Reverse bias is an increasingly common fault event that may be generated by user error, improperly installed batteries, automotive environments, erroneous connections to third-party chargers, negative “hot plug” transients, inductive transients, and readily available negatively biased rouge USB chargers.

Fairchild circuit protection is proud to offer a new type of reverse bias protection devices. The FR devices are low resistance, series switches that, in the event of a reverse bias condition, shut off power and block the negative voltage to help protect downstream circuits.

The FR devices are optimized for the application to offer best in class reverse bias protection and voltage capabilities while minimizing size, series voltage drop, and normal operating power consumption.

In the event of a reverse bias application, FR015L3EZ devices effectively provide a full voltage block and can easily protect -0.3V rated silicon.

From a power perspective, in normal bias, a 15mΩ FR device in a 0.1A application will generate only 1.5mV of voltage drop or 0.15mW of power loss. In reverse bias, FR devices dissipate less than 10μW in a 3V reverse bias event. This type of performance is not possible with a diode solution.

Benefits extend beyond the device. Due to low power dissipation, not only is the device small, but heat sinking requirements and cost can be minimized as well.

Ordering Information

| Part Number | Operating Temperature Range | Top Mark | Package | Packing Method |
|-------------|-----------------------------|----------|---|--|
| FR015L3EZ | -55°C ~ 125°C | 019L | 6-Lead, Molded Leadless Package (MLP), Dual, Non-JEDEC, 2mm Square, Single-Tied DAP | 3000 on Tape & Reel; 7-inch Reel, 12mm Tape |

Diagrams

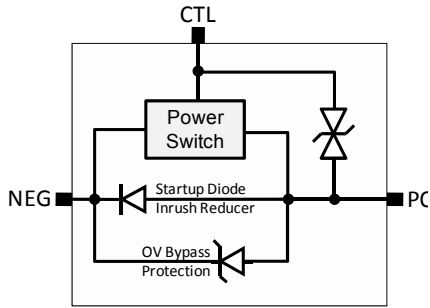


Figure 1. Block Diagram

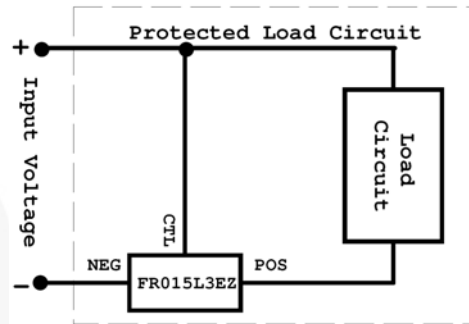
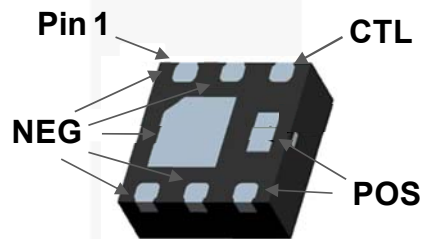


Figure 2. Typical Schematic

Pin Configuration



MicroFET 2x2 mm

Figure 3. Pin Assignments

Pin Definitions

| Name | Pin | Description |
|------|------------|---|
| POS | 4 | The ground of the load circuit to be protected. Current flows into this pin during normal bias operation. |
| CTL | 3 | The control pin of the device. A positive voltage on this pin with regard to NEG pin turns the switch on and a negative voltage turns the switch to a high impedance state. |
| NEG | 1, 2, 5, 6 | The ground of the input power source. Current flows out of this pin during normal bias operation. |

Absolute Maximum Ratings

Values are at $T_A=25^\circ\text{C}$ unless otherwise noted.

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | | Value | Unit | | |
|---------------------------|--|--|--|------------------|---|------|
| $V_{+ \text{ MAX_OP}}$ | Steady-State Normal Operating Voltage between CTL and NEG Pins ($V_{\text{IN}} = V_{+ \text{ MAX_OP}}$, $I_{\text{IN}} = 1.5\text{A}$, Switch On) | | +8 | V | | |
| $V_{+ 24}$ | 24-Hour Normal Operating Voltage Withstand Capability between CTL and NEG Pins ($V_{\text{IN}} = V_{+ 24}$, $I_{\text{IN}} = 1.5\text{A}$, Switch On) ⁽¹⁾ | | 12 | | | |
| $V_{- \text{ MAX_OP}}$ | Steady-State Reverse Bias Standoff Voltage between CTL and NEG Pins ($V_{\text{IN}} = V_{- \text{ MAX_OP}}$) | | -20 | | | |
| I_{IN} | Input Current | $V_{\text{IN}} = 3\text{V}$, Continuous ⁽²⁾ (see Figure 4) | 8 | A | | |
| T_{J} | Operating Junction Temperature | | 150 | $^\circ\text{C}$ | | |
| P_{D} | Power Dissipation | $T_{\text{A}} = 25^\circ\text{C}$ ⁽²⁾ (see Figure 4) | 2.4 | W | | |
| | | $T_{\text{A}} = 25^\circ\text{C}$ ⁽²⁾ (see Figure 5) | 0.9 | | | |
| $I_{\text{DIODE_CONT}}$ | Steady-State Diode Continuous Forward Current from POS to NEG | | 2 | A | | |
| $I_{\text{DIODE_PULSE}}$ | Pulsed Diode Forward Current from POS to NEG (300 μs Pulse) | | 190 | | | |
| ESD | Electrostatic Discharge Capability | Human Body Model, JESD22-A114 | | 2500 | V | |
| | | Charged Device Model, JESD22-C101 | | 2000 | | |
| | | System Model, IEC61000-4-2 | POS is shorted to CTL | Contact | | 5000 |
| | | | | Air | | 7000 |
| | | | No external connection between POS and CTL | Contact | | 300 |
| | | | | Air | | 3000 |

Notes:

- The V_{+24} rating is NOT a survival guarantee. It is a statistically calculated survivability reference point taken on qualification devices, where the predicted failure rate is less than 0.01% at the specified voltage for 24 hours. It is intended to indicate the device's ability to withstand transient events that exceed the recommended operating voltage rating. Specification is based on qualification devices tested using accelerated destructive testing at higher voltages, as well as production pulse testing at the V_{+24} level. Production device field life results may vary. Results are also subject to variation based on implementation, environmental considerations, and circuit dynamics. Systems should never be designed with the intent to normally operate at V_{+24} levels. Contact Fairchild Semiconductor for additional information.
- The device power dissipation and thermal resistance (R_{θ}) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 4 and Figure 5



Figure 4. 1 Square Inch of 2-ounce copper

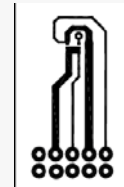


Figure 5. Minimum Pads of 2-ounce Copper

Thermal Characteristics

| Symbol | Parameter | Value | Unit |
|-----------------------|---|-------|--------------------|
| $R_{\theta\text{JA}}$ | Thermal Resistance, Junction to Ambient ⁽²⁾ (see Figure 4) | 60 | $^\circ\text{C/W}$ |
| $R_{\theta\text{JA}}$ | Thermal Resistance, Junction to Ambient ⁽²⁾ (see Figure 5) | 150 | |

Electrical Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------------------------------|---|---|---------------------|------|------|----------------------|
| Positive Bias Characteristics | | | | | | |
| R_{ON} | Device Resistance, Switch On | $V_{IN} = +1.7\text{V}, I_{IN} = 1.5\text{A}$ | | 22 | 30 | m Ω |
| | | $V_{IN} = +2.1\text{V}, I_{IN} = 1.5\text{A}$ | | 18 | 25 | |
| | | $V_{IN} = +3\text{V}, I_{IN} = 1.5\text{A}$ | | 15 | 20 | |
| | | $V_{IN} = +5\text{V}, I_{IN} = 1.5\text{A}$ | | 14 | 19 | |
| | | $V_{IN} = +3\text{V}, I_{IN} = 1.5\text{A}, T_J = 125^\circ\text{C}$ | | 22 | 30 | |
| V_{ON} | Input Voltage, V_{IN} , at which Voltage at POS, V_{POS} , Reaches a Certain Level at Given Current | $I_{IN} = 100\text{mA}, V_{POS} = 50\text{mV}, V_{NEG} = 0\text{V}$ | 0.7 | 1.0 | 1.3 | V |
| $\Delta V_{ON} / \Delta T_J$ | Temperature Coefficient of V_{ON} | | | -1.7 | | mV/ $^\circ\text{C}$ |
| I_{DIODE_CONT} | Continuous Diode Forward Current | $V_{CTL} = V_{POS}$ | | | 2 | A |
| V_F | Diode Forward Voltage | $V_{CTL} = V_{POS}, I_{DIODE} = 3\text{A},$ Pulse width < 300 μs | 0.65 | 0.80 | 0.95 | V |
| I_{BIAS} | Bias Current Flowing out of NEG Pin during Normal Bias Operation | $V_{CTL} = 8\text{V}, V_{NEG} = 0\text{V},$ No Load | | | 10 | μA |
| Negative Bias Characteristics | | | | | | |
| V_{-MAX_OP} | Reverse Bias Breakdown Voltage | $I_{IN} = -250\mu\text{A}, V_{CTL} = V_{POS} = 0\text{V}$ | | | -20 | V |
| $\Delta V_{-MAX_OP} / \Delta T_J$ | Reverse Bias Breakdown Voltage Temperature Coefficient | | | 16 | | mV/ $^\circ\text{C}$ |
| I_{-} | Leakage Current from NEG to POS in Reverse-Bias Condition | $V_{NEG} = 16\text{V},$ $V_{CTL} = V_{POS} = 0\text{V}$ | | | 1 | μA |
| t_{RN} | Time to Respond to Negative Bias Condition | $V_{NEG} = 2.7\text{V}, V_{CTL} = 0\text{V},$ $C_{LOAD} = 10\mu\text{F},$ Reverse Bias Startup Inrush Current = 0.2A | | | 50 | ns |
| Integrated TVS Performance | | | | | | |
| V_Z | Breakdown Voltage @ I_T | $I_T = 1\text{mA}$ | 12 | 13 | 14.5 | V |
| I_R | Leakage Current from CTL to POS, NEG is Open | $V_{CTL} - V_{POS} = 8\text{V}$ | | 2 | 10 | μA |
| | | $V_{CTL} - V_{POS} = -8\text{V}$ | | -2 | -10 | |
| I_{PPM} | Max Pulse Current from CTL to POS | IEC61000-4-5 8x20 μs pulse, NEG is Open | $V_{CTL} > V_{POS}$ | | 0.6 | A |
| | | | $V_{CTL} < V_{POS}$ | | 0.4 | |
| V_C | Clamping Voltage form CTL to POS | | $V_{CTL} > V_{POS}$ | | 15.0 | V |
| | | | $V_{CTL} < V_{POS}$ | | 14.3 | |
| Dynamic Characteristics | | | | | | |
| C_i | Input Capacitance between CTL and NEG | $V_{IN} = 3\text{V}, V_{NEG} = V_{POS} = 0\text{V},$ $f = 1\text{MHz}$ | | 900 | | pF |
| C_s | Switch Capacitance between POS and NEG | | | 133 | | |
| C_o | Output Capacitance between CTL and POS | | | 967 | | |
| R_C | Control Internal Resistance | | | 2 | | |

Typical Characteristics

$T_J = 25^\circ\text{C}$ unless otherwise specified.

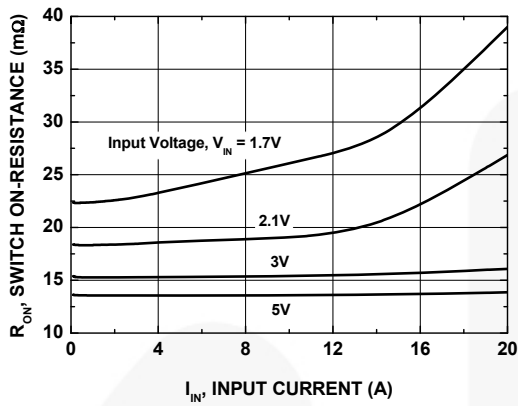


Figure 6. Switch On Resistance vs. Switch Current

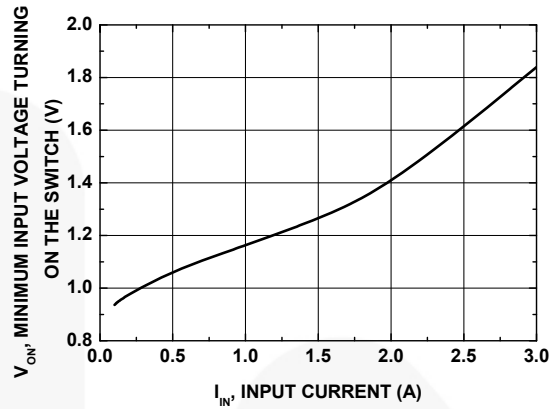


Figure 7. Minimum Input Voltage to Turn On Switch vs. Current at 50mV Switch Voltage Drop

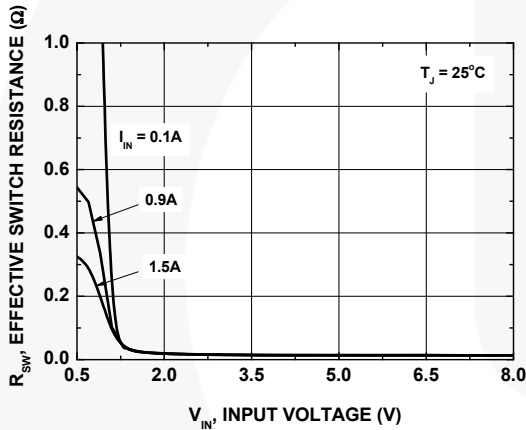


Figure 8. Effective Switch Resistance R_{SW} vs. Input Voltage V_{IN}

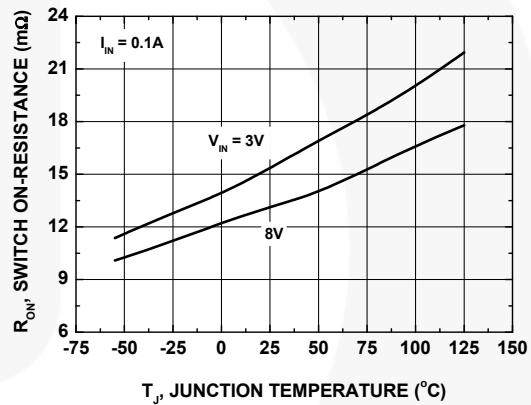


Figure 9. Switch On Resistance vs. Junction Temperature at 0.1A

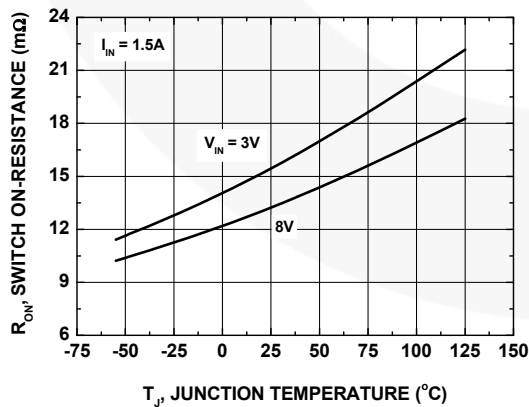


Figure 10. Switch On Resistance vs. Junction Temperature at 1.5A

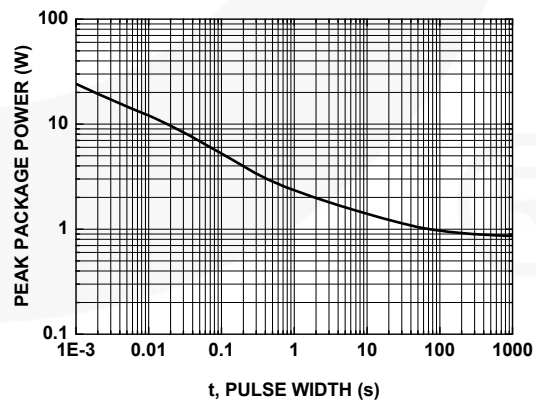


Figure 11. Single-Pulse Maximum Power vs. Time

Typical Characteristics (Continued)

$T_J = 25^\circ\text{C}$ unless otherwise specified.

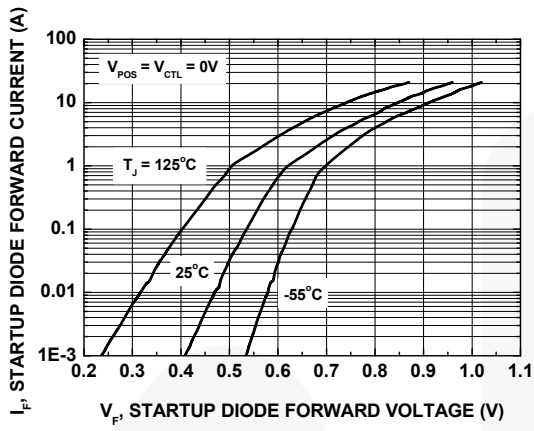


Figure 12. Startup Diode Current vs. Forward Voltage

Application Test Configurations

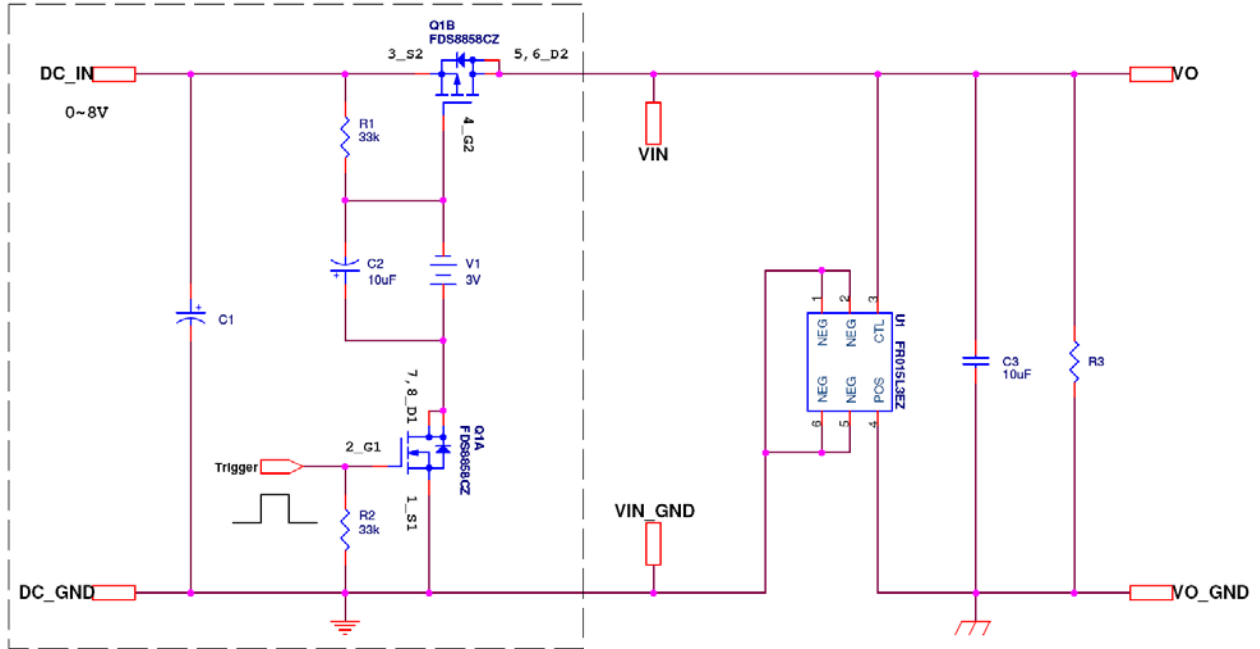


Figure 13. Startup Test Circuit – Normal Bias with FR015L3EZ Device

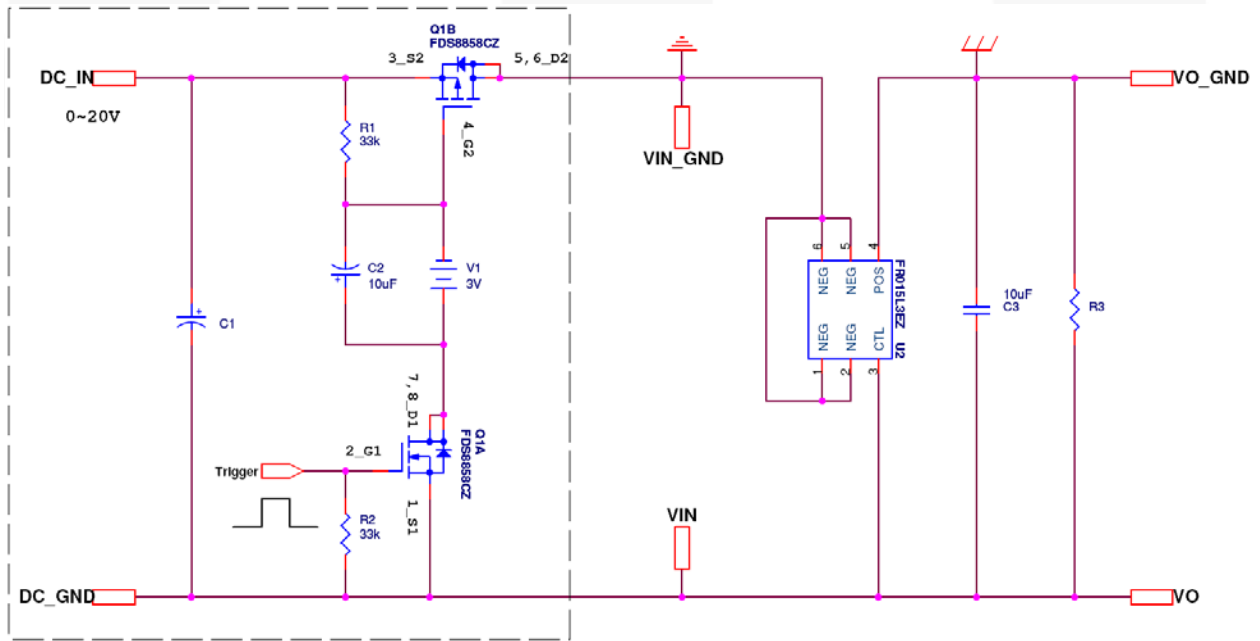


Figure 14. Startup Test Circuit – Reverse Bias with FR015L3EZ Device

Application Test Configurations

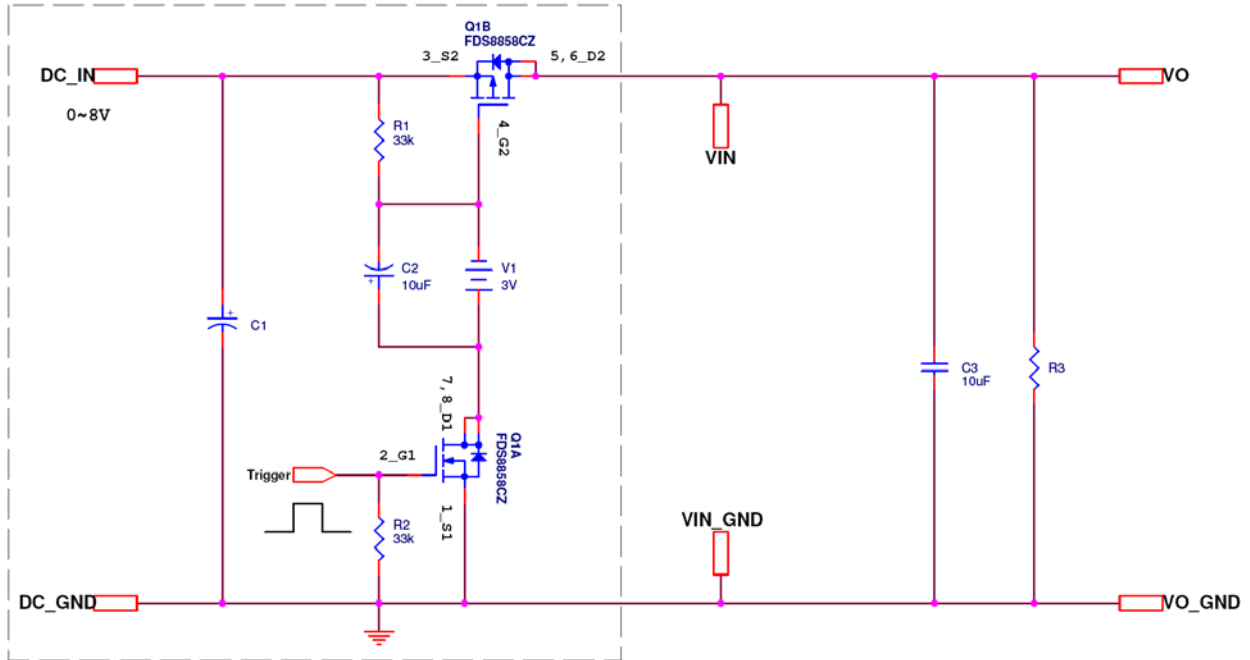


Figure 15. Startup Test Circuit – No Reverse Polarity Protection

Typical Application Waveforms

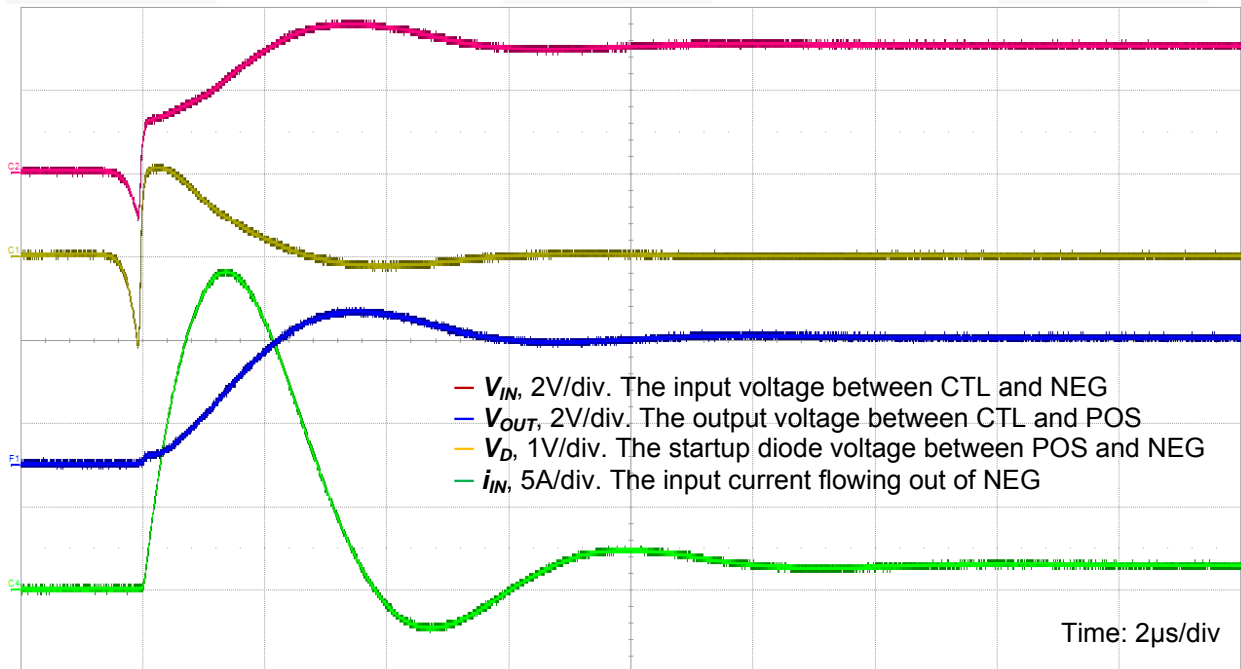


Figure 16. Normal Bias Startup Waveform, $V_{IN}=3V$, $V_1=3V$, $C_1=5200\mu F$, $C_2=C_3=10\mu F$, $R_1=R_2=33k\Omega$, $R_3=2\Omega$

Typical Application Waveforms (Continued)

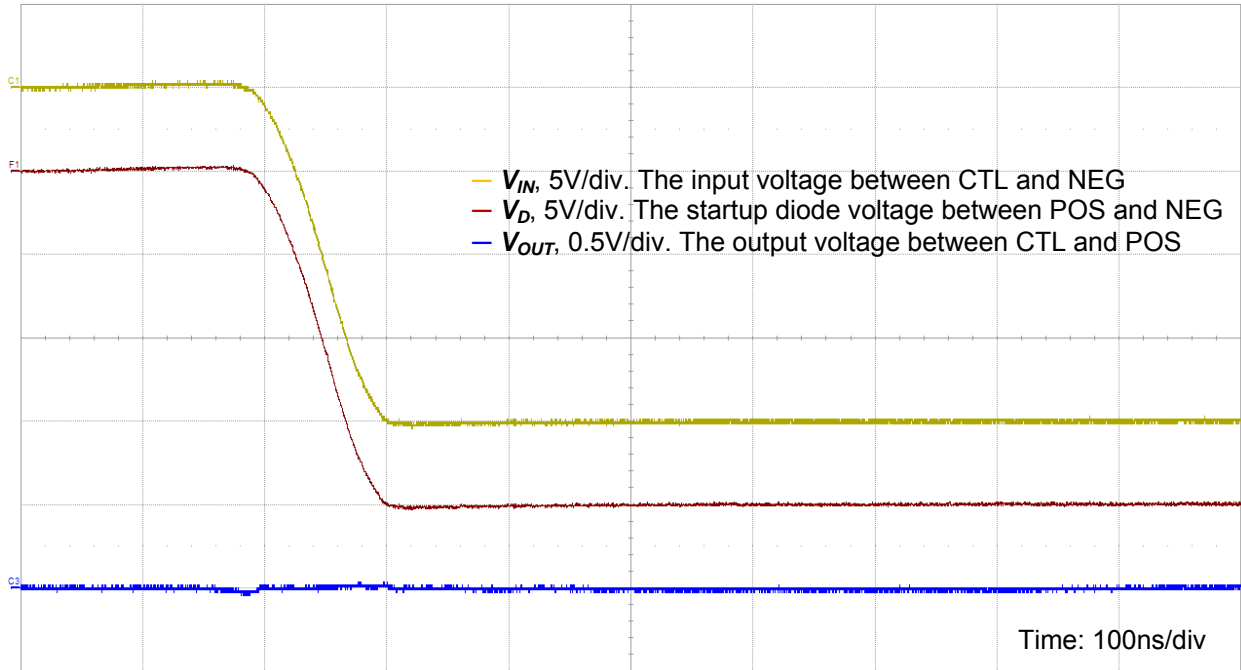


Figure 17. Reverse Bias Startup Waveform, $V_{IN}=3V$, $V_1=3V$, $C_1=5200\mu F$, $C_2=C_3=10\mu F$, $R_1=R_2=33k\Omega$, $R_3=2\Omega$

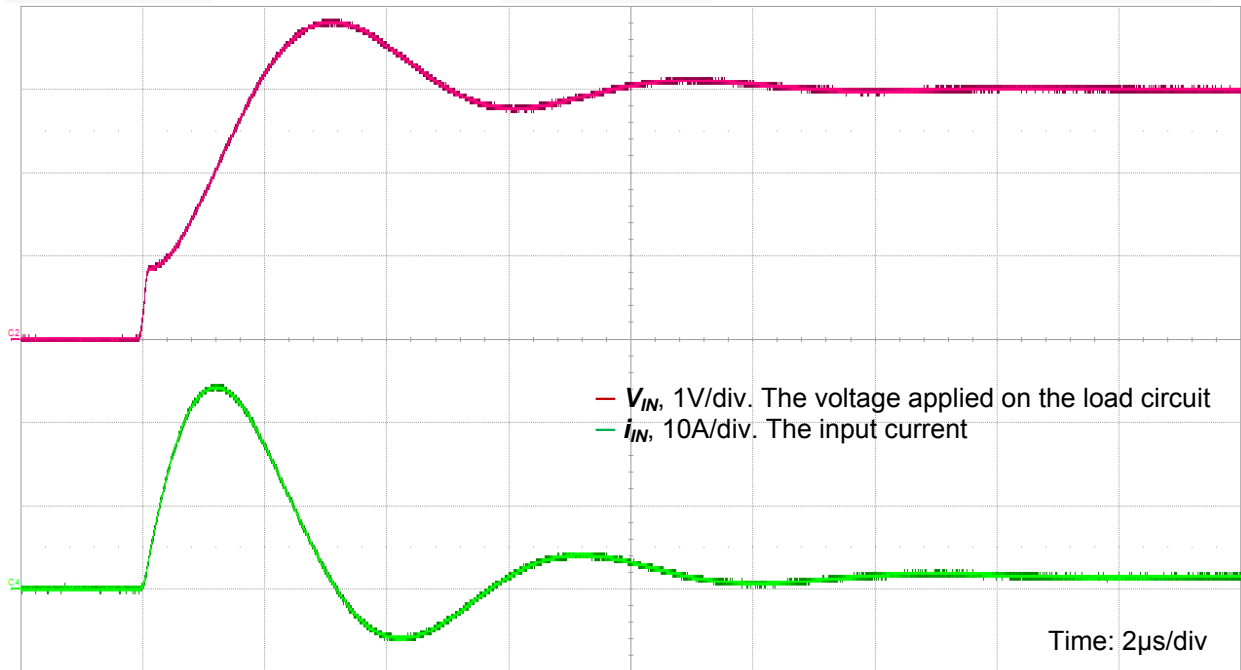


Figure 18. Startup Waveform without FR015L3EZ Device, $V_{IN}=3V$, $V_1=3V$, $C_1=5200\mu F$, $C_2=C_3=10\mu F$, $R_1=R_2=33k\Omega$, $R_3=2\Omega$

Application Information

The FR015L3EZ is capable of being turned on at a voltage as low as 1.5V, therefore is especially suitable for low voltage application like AA, AAA or single lithium-ion battery operated devices. The voltage and current waveforms in Figure 16 and Figure 18 are both captured with a 2Ω load at 3V input.

When the DC power source is connected to the circuit (refer to Figure 1 and Figure 2), the built-in startup diode initially conducts the current such that the load circuit powers up. Due to the initial diode voltage drop, the FR015L3EZ effectively reduces the peak inrush current of a hot plug event. Under these test conditions, the input inrush current reaches about 19A peak. While the current flows, the input voltage increases. The speed of this input voltage increase depends on the time constant formed by the load resistance R_3 and load capacitance C_3 , assuming the input voltage source holds itself during turn on. The larger the time constant, the slower the input voltage increase. As the input voltage approaches a level equal to the protector's turn-on voltage, V_{ON} , the protector turns on and operates in Low-Resistance Mode as defined by V_{IN} and operating current I_{IN} .

In the event of a negative voltage transient between CTL and NEG, or when the DC power source, V_{IN} , is reversely connected to the circuit, while no residual voltage presents between CTL and POS, the device blocks the flow of current and holds off the voltage, thereby protecting the load circuit. Figure 17 shows the startup waveforms while a passive load circuit is reversely biased. It can be clearly seen that the output voltage is near 0 or at a level that is harmless to the load circuit.

Figure 18 shows the voltage and current waveforms when no reverse bias protection is implemented. In

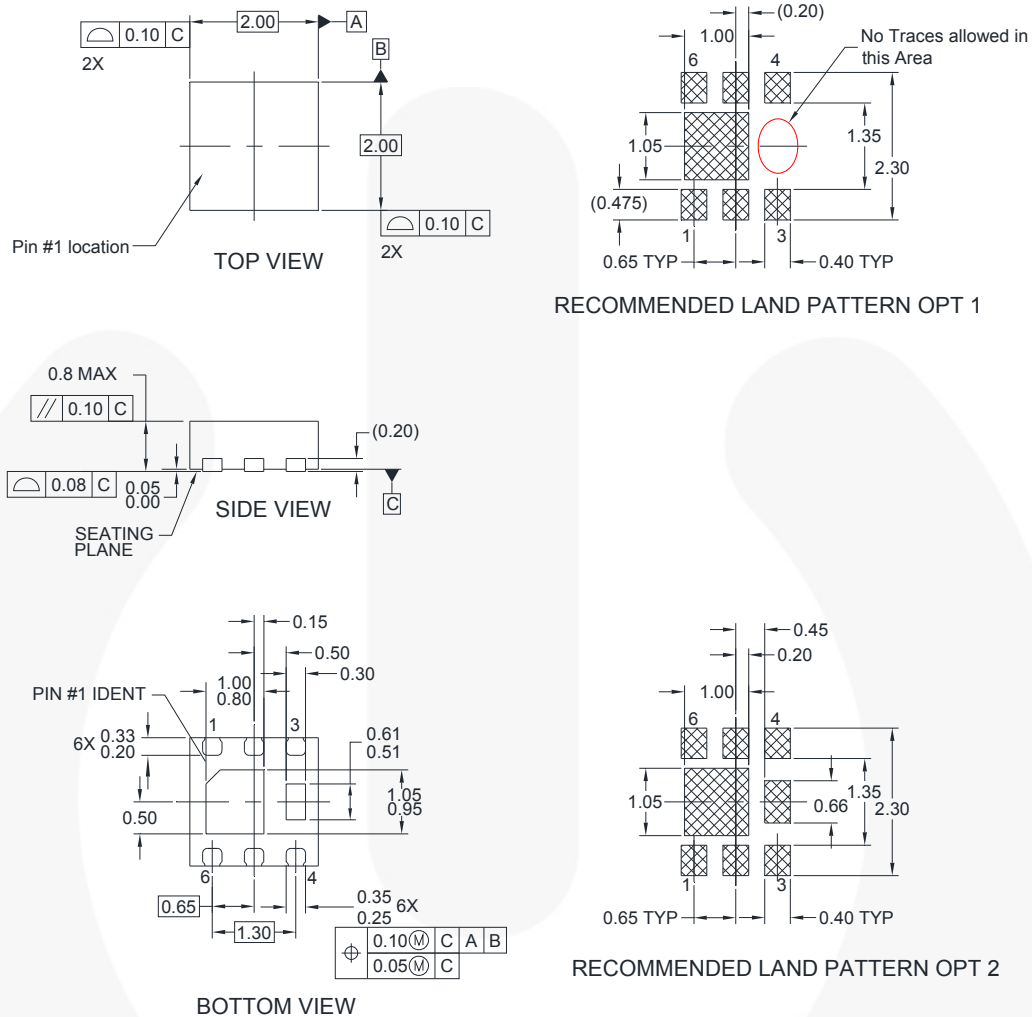
Figure 16, while the reverse bias protector is present, the input voltage, V_{IN} , and the output voltage, V_O , are separated and look different. When this reverse bias protector is removed, V_{IN} and V_O merge, as shown in Figure 18 as V_{IN} . This V_{IN} is also the voltage applied to the load circuit. It can be seen that, with reverse bias protection, the voltage applied to the load and the current flowing into the load look very much the same as without reverse bias protection.

In Figure 16, negative voltage spikes are seen on V_{IN} and V_D before V_{IN} starts to rise from 0; and in both Figures 16 and 18, negative input current is seen after FR015L3EZ is fully turned on. These phenomena are a combined effect of parasitic inductance and all the capacitors in the input voltage control circuit enclosed in the broken line as shown in Figures 13 to 15. This is not a problem as long as the load circuit doesn't see a negative voltage at anytime, which is what the reverse bias protector is meant for. Indeed, we can see from Figures 16 and 18, the output voltage on the load circuit is always equal to or greater than 0V.

Benefits of Reverse Bias Protection

The most important benefit is, of course, to prevent accidentally reverse-biased voltage from damaging the load circuit. Another benefit is that the peak startup inrush current can be reduced. How fast the input voltage rises, the input/output capacitance, the input voltage, and how heavy the load is determine how much the inrush current can be reduced. In this specific 3V / 2A application, for example, the inrush current has been reduced from 24A to 19A, a 21% reduction. This can offer a system designer the option of increasing C_3 while keeping "effective" load circuit capacitance down.

Physical Dimensions



NOTES:

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-229 DATED AUG/2003
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DRAWING FILENAME: MKT-MLP06Lrev3.

Figure 19. 6-Lead, Molded Leadless Package (MLP), Dual, Non-JEDEC, 2mm Square, Single-Tied DAP

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.





Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:
<http://www.fairchildsemi.com/packaging/>.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:
http://www.fairchildsemi.com/products/discrete/pdf/mlp2x2_tr.pdf



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|--|--|--|--|
| 2Cool™ | F-PFS™ | PowerTrench® | The Power Franchise® |
| AccuPower™ | FRFET® | PowerXS™ | the power franchise |
| AX-CAP™* | Global Power Resource™ | Programmable Active Droop™ | TinyBoost™ |
| BitSiC™ | GreenBridge™ | QFET® | TinyBuck™ |
| Build it Now™ | Green FPS™ | QS™ | TinyCalc™ |
| CorePLUS™ | Green FPS™ e-Series™ | Quiet Series™ | TinyLogic® |
| CorePOWER™ | Gmax™ | RapidConfigure™ | TINYOPTO™ |
| CROSSVOL™ | GTO™ |  ™ | TinyPower™ |
| CTL™ | IntelliMAX™ | Saving our world, 1mW/W/kW at a time™ | TinyPWM™ |
| Current Transfer Logic™ | ISOPLANAR™ | SignalWise™ | TinyWire™ |
| DEUXPEED® | Making Small Speakers Sound Louder and Better™ | SmartMax™ | TranSiC™ |
| Dual Cool™ | MegaBuck™ | SMART START™ | TriFault Detect™ |
| EcoSPARK® | MICROCOUPLER™ | Solutions for Your Success™ | TRUECURRENT®* |
| EfficientMax™ | MicroFET™ | SPM® | µSerDes™ |
| ESBC™ | MicroPak™ | STEALTH™ |  SerDes |
|  Fairchild® | MicroPak2™ | SuperFET® | UHC® |
| Fairchild Semiconductor® | MillerDrive™ | SuperSOT™-3 | Ultra FRFET™ |
| FACT Quiet Series™ | MotionMax™ | SuperSOT™-6 | UniFET™ |
| FACT® | mWSaver™ | SuperSOT™-8 | VCC™ |
| FAST® | OptoHiT™ | SupreMOS® | VCX™ |
| FastvCore™ | OPTOLOGIC® | SyncFET™ | VisualMax™ |
| FETBench™ | OPTOPLANAR® | Sync-Lock™ | VoltagePlus™ |
| FlashWriter®* | |  SYSTEM GENERAL®* | XS™ |
| FPS™ | | | |

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|-----------------------|---|
| Advance Information | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
| Obsolete | Not In Production | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only. |

Rev. I62